SEMICONDUCTOR DEVICE TESTING AND BURN-IN METHODOLOGY

ABSTRACT

A packaged semiconductor device and a method for burn-in and testing are disclosed. The package comprises a carrier having a pattern of contact pads for electrical connection, and also a pattern of testing pads for electrical characterization such that their location, size and composition allows a conversion to contact pads after the device has been electrically characterized following burn-in. Furthermore, an adapter and a method for burn-in and testing are disclosed for use in testing a variety of different semiconductor devices. The adapter comprises a carrier having a pattern of testing pads bordering the carrier outline, and routing strips which are structured such that the carrier is adaptable to the package of the device being tested.

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